The HR 550 hybrid rework system addresses all users with highest requirements in terms of precision and process safety in electronic assembly rework applications.

The HR 550 provides a 1,500 W high-performance hybrid heating element to desolder and solder SMT components up to dimensions of 70 x 70 mm! A 2,400 W infrared bottom heater with three heating zones guarantees homogeneous bottom-side preheating of the complete assembly.

Non-contact and contacting temperature sensing directly at the component as well as an optimized process control guarantee ideal removal and installation processes of various component types.

A high-precision vacuum pipette, integrated into the units heating head, operates component removal and placement. Stepper motors for the exchangeable hybrid heating head and the vacuum pipette supply exact movement during component desoldering and installation. An integrated force sensor recognizes when component and printed circuit board are contacted. Ergonomically arranged control elements and computer-aided component alignment by means of high-contrast, high-definition camera images are special highlights for the operator.

The HR 550 is prepared for operation with the Kurtz Ersa DIP&PRINT STATION. The rework system is operated via a newly developed software and ergonomically arranged operating elements on the station.
**Technical data:**

- Dimensions (W x D x H): 573 x 765 x 545/747 mm (heating head top/bottom)
- Weight: 76 kg
- Supply voltage: 220 - 240 V AC, 50 - 60 Hz, 16 A
- Top heater data: 70 x 70 mm, 900 W convection + 600 W infrared
- Top heater technology: Hybrid heating element with medium wave IR radiators and additional hot-air heating
- Bottom heater data (W x D): 390 x 270 mm, 2,400 W in three zones
- Bottom heater technology: Medium wave infrared radiator with mesh grid cover
- PCB dimensions (W x D): 382 mm x 300 (+x) mm
- Working depth: 349 mm
- Working distance (typ.): 30 - 60 mm to top heater, 35 mm to bottom heater
- Component dimensions: 0.5 x 0.5 to 70 x 70 mm
- Positioning laser: Class II
- Field of view placement camera: 70 x 70 mm (wide angle) 25 x 33 mm (tele)
- Operating software: HRSoft 2 – suitable for Windows 8 and Windows 10

**Order information:**

<table>
<thead>
<tr>
<th>Order No.</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>OHR550</td>
<td>Kurtz Ersa HR 550 Hybrid Rework System</td>
</tr>
<tr>
<td>OHR510</td>
<td>RPC Kamera HR 550</td>
</tr>
<tr>
<td>OPR100</td>
<td>Dip&amp;Print Station complete</td>
</tr>
</tbody>
</table>

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**Further information on our website:**

![QR Code](QR_CODE_URL)

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![Image 1](IMAGE_URL1)

**Computer aided adjustment of a QFP, green: pads, red: component pins, blue: overlay "best match"**

![Image 2](IMAGE_URL2)

**Optional reflow process camera**

![Image 3](IMAGE_URL3)

**HRSoft 2 with new, intuitive operation surface**

![Image 4](IMAGE_URL4)

**Flexible PCB holder**

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**Kurtz Ersa HR 550 hybrid rework system – rework at the highest level**

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